FIT Hon Teng Limited 鴻騰六零八八精密科技股份有限公司

1H23 Results Announcement

二零二三年中期度業績發佈會



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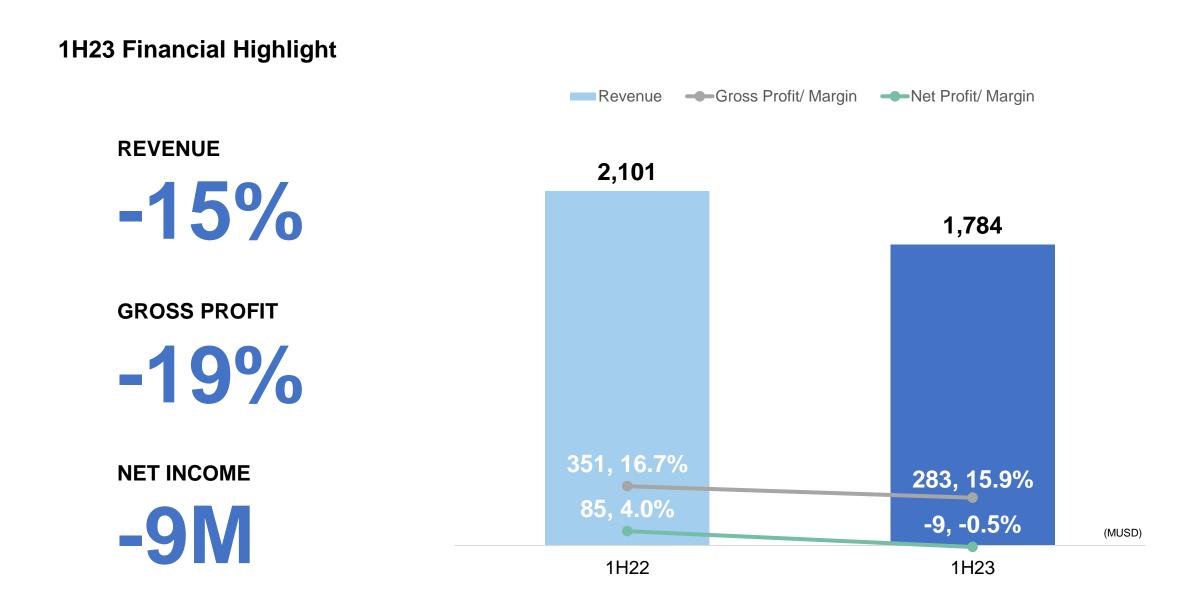
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Agenda

1H23 Financial Overview 3Q23 & 2H23 Guidance Execution Status Update News Update ESG Q&A Section FJ

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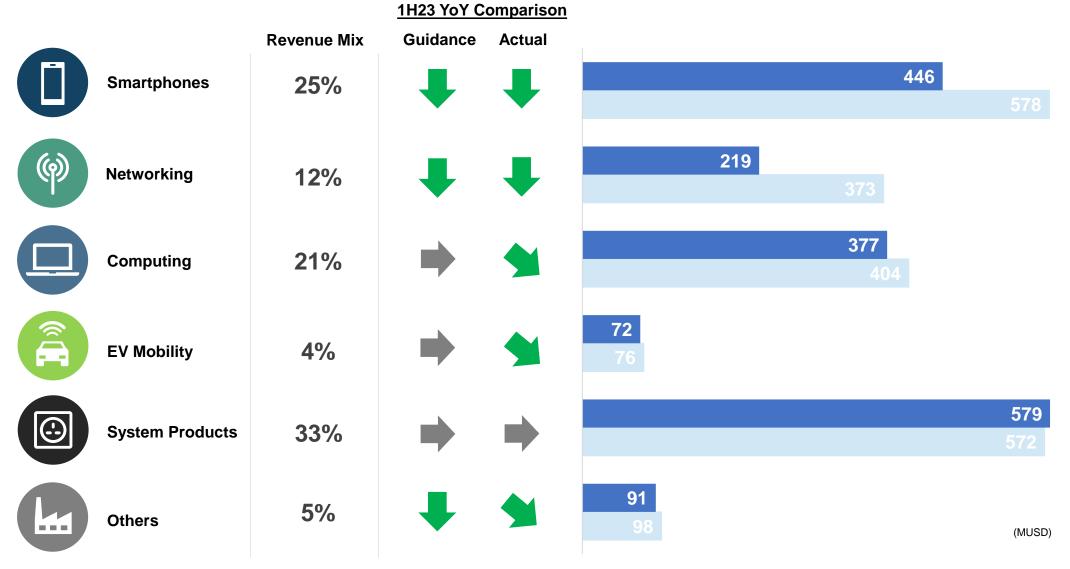
Financial Highlight



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1H23 Segment Performance



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Financial Guidance

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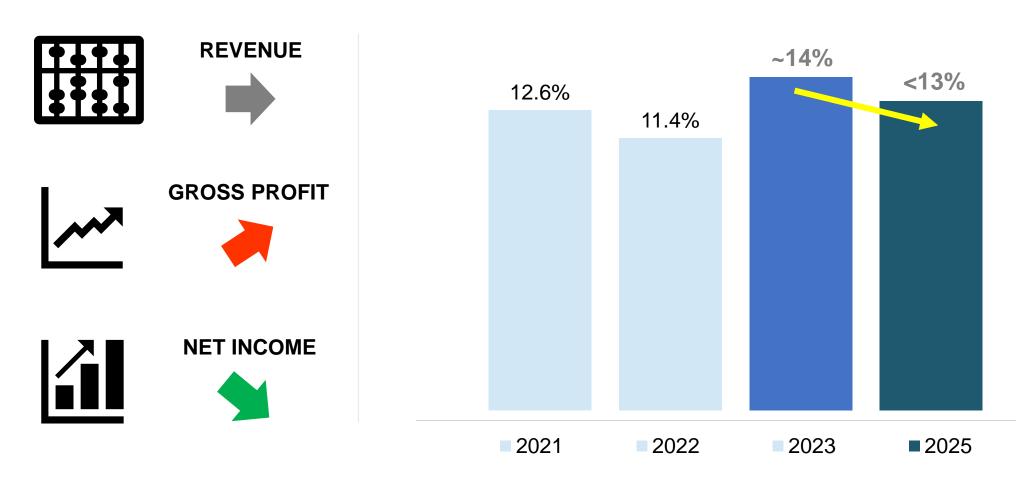
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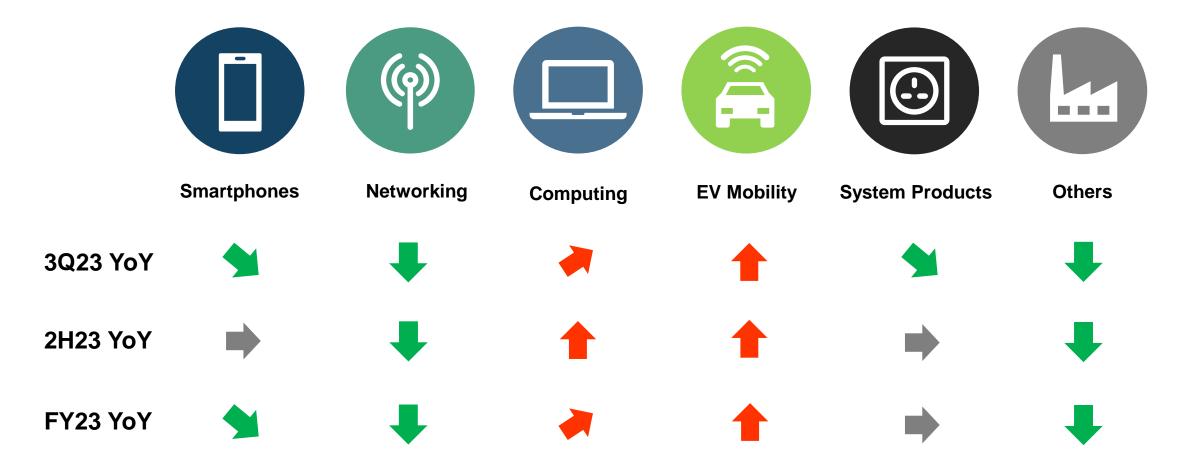
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Full Year Guidance Recap

2023 YoY



OPEX Ratio Forecast



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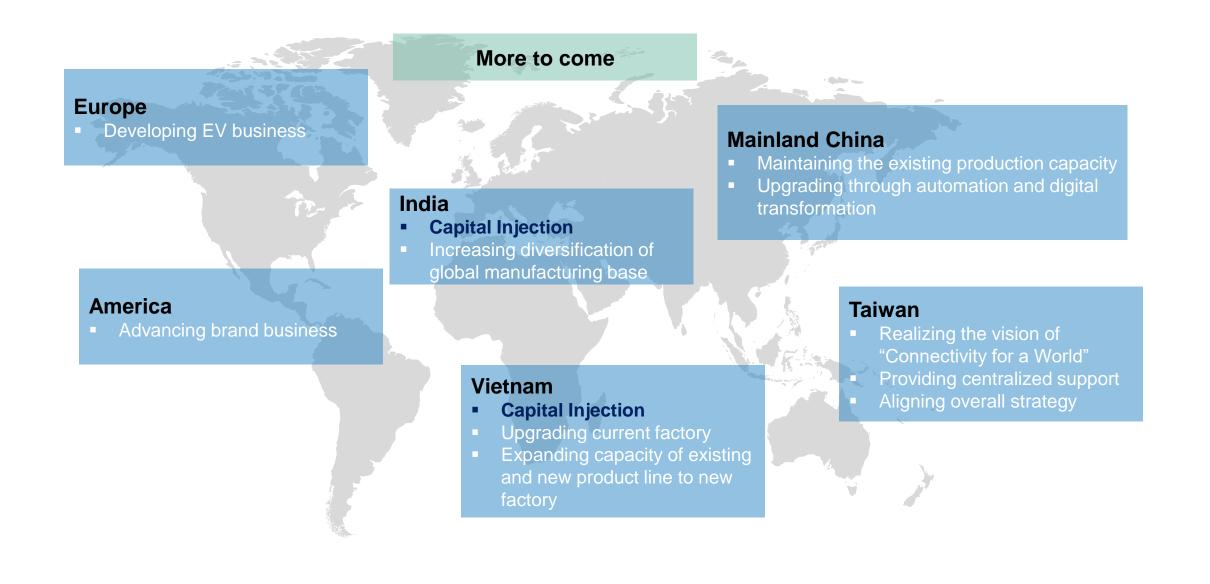
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Execution Status Updates

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Expand Global Services as Industry Trend Diversifies Footprint



CAPEX Distribution Forecast

	(MUSD)	2023 (F)	2024 (F)	2025 (F)	
By Purpose	Total	~800	950 - 980	400 - 430	
Property & Plant					
Vietnam Expansion		6%	11%	16%	
India Expansion		21%	22%	0%	
Equipment		73%	67%	84%	
Equipment By Strategy					
EV Mobility		40%	7%	17%	
5G AloT		14%	24%	34%	
Audio		8%	41%	6%	
Legacy Product		38%	28%	44%	

1H23 3+3 Execution Status Update

Revenue Mix Forecast Update



EV Mobility

• New EV business unit developed – FIT Voltaira



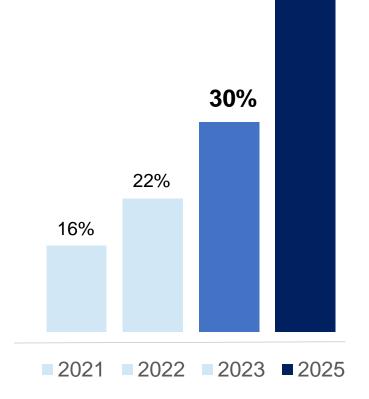
New Generation 5G AloT

- Key focus for mid-term profit growth
- Winning Reddot Award 800G Product
- OCP market opportunities development



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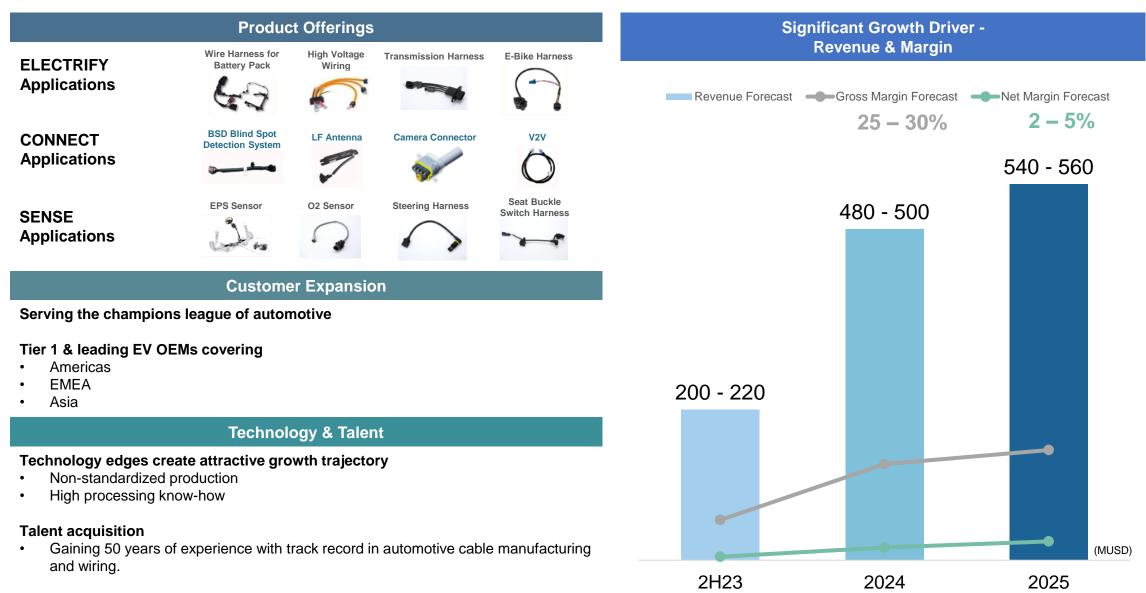
• Preparation of global service expansion



40%

Enhancing EV Strengths – FIT Voltaira

Completed Acquisition of Prettl SWH Group and Introduces New EV Business Unit - FIT Voltaira



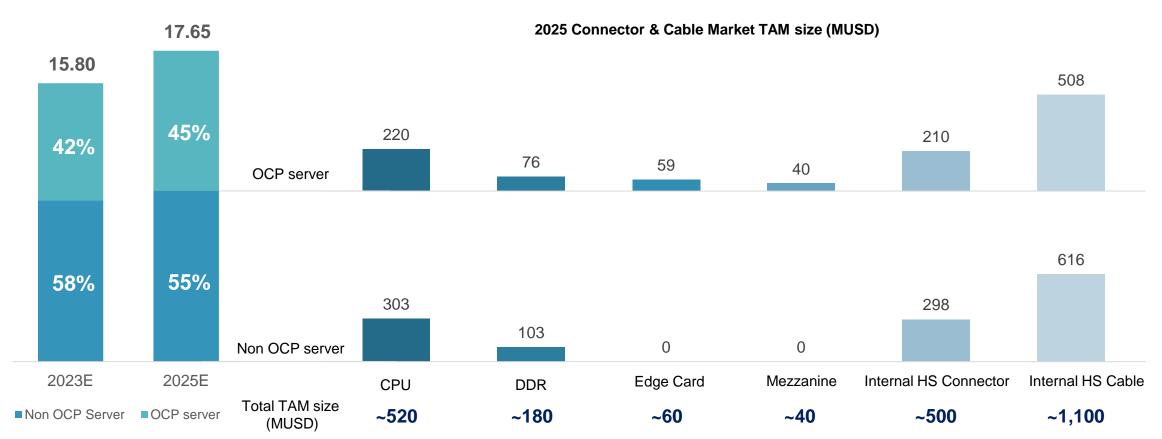
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5G AloT Certified Products Meet Industry Trend

	Energy Saving	Power Efficiency	Open Standard
Industry Trend	Moving away from traditional air cooling towards liquid cooling	Moving away from traditional PSU towards power shelves, uninterrupted power systems	Moving away from unique architecture designs towards the development of open specifications and standards
FIT accomplished	CPU socket & DDR passed the liquid cooling environment test	MCRPS connectors mass-produced & entered association standards	Opened an alliance corresponding M-XIO EDSFF product matching

AI Opens up OCP Market Opportunities

2023 – 2025 Worldwide Server Shipment Forecast (M unit)

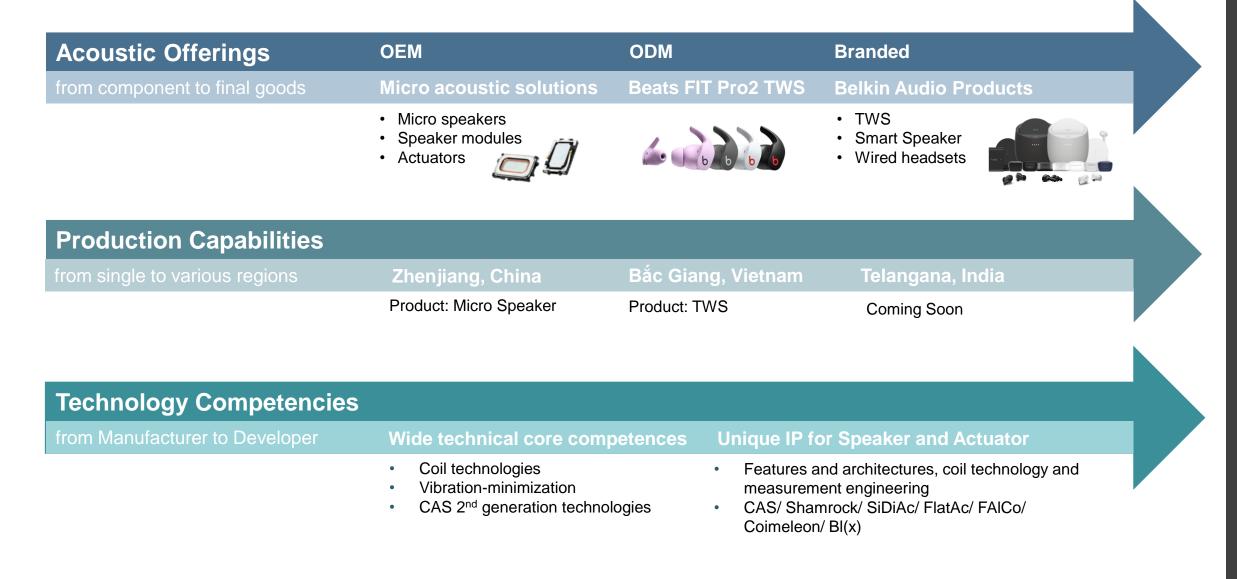


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News Updates

Recent Announcements



清腹六零八八根密科技股份有限公司 (Incorporated in the Cayman Islands with Emited liability under the name Foncorn Interconnect Technology Limited and carrying on business in Hong Kong as IFTI Hon Tang Limited) (Stock Code: 6088)

VOLUNTARY ANNOUNCEMENT

This is a voluntary announcement made by FIT Hon Teng Limited* (the "Company").

The board of directors of the Company (the "Board") is pleased to announce that (i) the Company proposed to make a capital injection of US\$500,000,000 to Foxconn Interconnect Technology Singapore Pre. L4d. ("FIT Singapore"), a direct wholly-owned subsidiary of the Company; (ii) FIT Singapore proposed to make a capital injection of US\$100,000,000 to Fu Wing Interconnect Technology (Nghe An) Company Limited, an indirect wholly-owned subsidiary of the Company; and (iii) FIT Singapore proposed to make a capital injection of US\$400,000,000 to Chang Yi Interconnect Technology (India) Private Limited, which is held by FIT Singapore as to 99,99% of the capital stock.

> By order of the Board FIT Hon Teng Limited* LU Sung-Ching Chairman of the Board

Hong Kong, August 7, 2023

As of the date of this announcement, the Board comprises Mr. LU Sung-Ching, Mr. LU Pochin Christopher and Mr. PIPKIN Chester John as executive directors, Mr. TRANOR-DIGGIROIAMO Sheldon and Ms. HUANG Pi-Chun as non-executive directors, and Mr. CURWEIN Peter D, Mr. TANG Kwai Chang and Mr. CHAN Wing Yuen Hubert as independent hon-executive directors.

Incorporated in the Cayman Idands with limited liability under the name Foncorn Interconnect Technology Limited and cattying on business in Hong Kong as FIT Hon Teng Limited



科技網 > 產業 > CarTech/綠能

PRETTL SWH集團更名FIT Voltaira加入鴻騰陣容

杜念魯/台北 2023-07-04

為進一步擴充在電動車關鍵零組件領域的實 力,符合今後轉型發展策略上的需求,鴻海旗 下鴻騰精密科技(FIT)於2023年初宣布以 1.86 億歐元(約新台幣 61 億元)購併德國車 用元件設計製造業者PRETTL SWH 集團。鴻 騰於3日晚間宣布已經完成此購併案。

鴻海旗下鴻騰報捷 再憑高速連接器獲紅點設計大獎

2023/06/27 11:25 回應(0) 人氟(311) 收藏(0)

MoneyDJ新聞 2023-06-27 11:25:16 記者 新聞中心 報導



設計大獎」。鴻德掌握最火紅的AI話題, 以「FITCONN」為題立憑藉創新800G高 速連接器展現出色的設計能力,獲得設計 概念獎。這項創新的解決方案在遵守既有 數據中心的規格和設計規則的同時,也大 力提高了數據傳輸效率。

鴻海(2317)旗下鴻騰精密科技(6088.HK)

再次獲得譽為「設計界奧斯卡」的「紅點

鴻腸指出,近年提出3+3策略發展電動 車、聲學及5GAIoT領域,並掌握數據中 心領域的最新趨勢,在5GAIoT領略中鎖 定「更節能(More Energy Saving)、更 效率(More Power Efficiency)、更開放 的平台(More Open Platforms)」三大 方針,透過其優異技術,持編掌握高毛利

的生意機會。

此產品不僅是在外觀做了改變,更徹底打破ASIC晶片堆疊的傳統設計,允許訊號直 接通過晶片上的接觸點與跳線連接器,有效消除訊號的損耗,縮短晶片和連接器間的 路徑,最大限度地提高了傳輸效率。

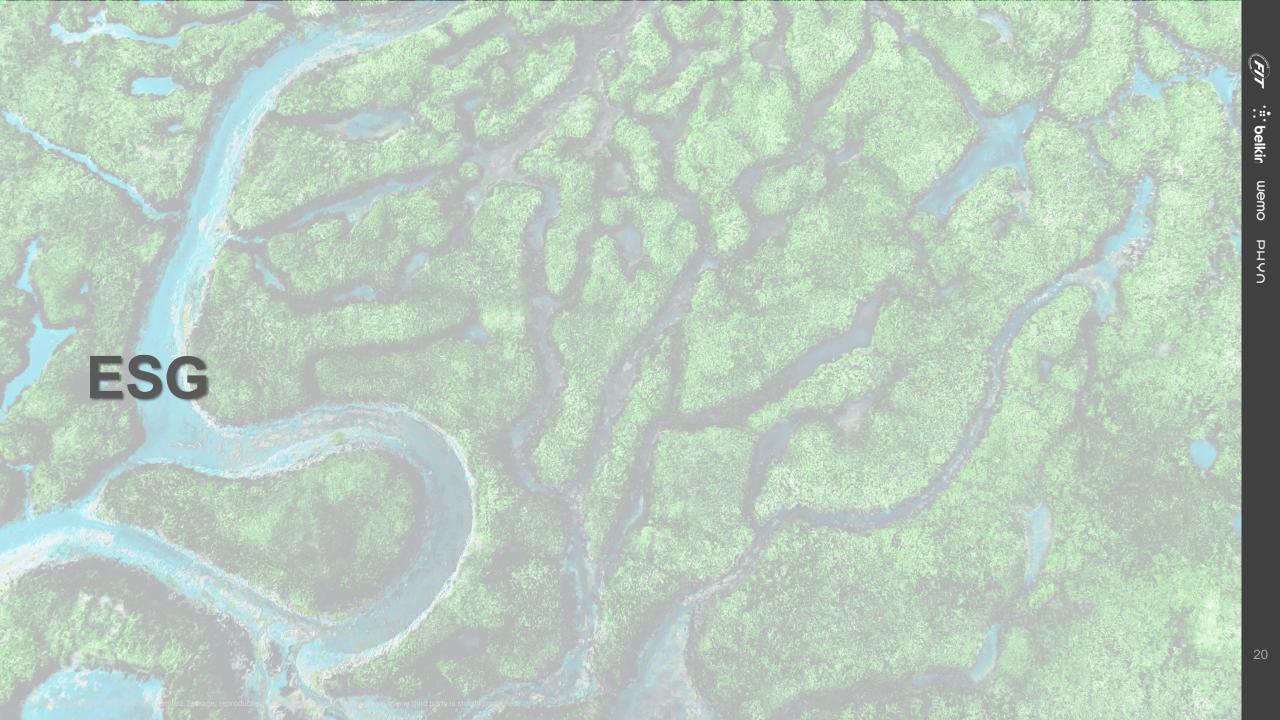
Foxconn electronics manufacturing facility in Telangana: Groundbreaking ceremony conducted

Groundbreaking ceremony for Foxconn Interconnect Technology's new electronics manufacturing facility was conducted at Kongara Kalan





7 August Capital Injection 3 July Prettl SHW Acquisition 27 June Reddot Awarded 800G Innovation 15 May India Groundbreaking



Honour and recognition of FIT in 2022



Hang Seng Corporate Sustainability Index Series Member 2022-2023

FIT receives A rating in Hang Seng Corporate Sustainability Index Series

The Hang Seng Corporate Sustainability Index Series evaluates a corporate's maturity in managing 7 Aspect Subjects covering ESG, FIT is accredited with A rating in 2022, with top 20% position as compared with peers.

Factories Recognitions



ABCD HAS ACHIEVED ZERO WASTE TO LANDFILL PLATINUM OPERATIONS, 100% DIVERSION UL.COM/ECV

UL 2799A

PLATINUM

FIT Mainland China factories Zero Waste Project

In line with Apple's waste management policy, FIT participated in Zero Waste Project in 2022. Apple requires suppliers to divert 100% of their waste from landfill, with a maximum of 10% sent to a waste-to-energy facility, in order to achieve the Zero Waste-to-Landfill certification through Underwriters Laboratories (UL). A project team was formed by the Environmental Engineering Department and led by various business units of different factories. Currently, Shenzhen and Kunshan factories have passed the annual validation this year and obtained UL2799 platinum certification. We target to extend the project to other factories in Mainland China and obtain relevant certifications.

FIT Shenzhen and Chongqing factories "Green Trustworthy Enterprises"

In the first environmental protection credit assessment by the Shenzhen Municipal Government, the Shenzhen factory was recognised as the highest level "Green Trustworthy Enterprise" among over 800 enterprises. The Chongqing factory also won the title of "Integrity Enterprise" in environmental protection credit rating.

FIT Huaian factory

"2022 Outstanding Enterprises in Ecological and Environmental Protection"

In January 2023, Huaian factory was selected as one of the corporates in attaining the "Outstanding Enterprises in Ecological and Environmental Protection" by Huaian Economic & Technological Development Zone of Huaian Ecological Environment Bureau.

Q&A section





Foxconn Interconnect Technology Limited (Incorporated in the Cayman Islands and carrying on business in Hong Kong as FIT Hon Teng Limited) 鴻騰精密科技股份有限公司 (於開曼群島成立 · 並以鴻騰六零八八精密科技股份有限公司於香港經營業務)

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Appendix



Statement of Comprehensive Income

(M'USD)	1H23	1H22	YoY
Revenue	1,784	2,101	-15%
Gross Profit	283	351	-19%
Gross Profit Margin	16%	17%	-85 bps
Operating Profit	25	88	-72%
Profit before Tax	7	107	-93%
Income Tax Expense	(16)	(22)	-27%
Profit for the Year	(9)	85	-111%
Profit Attributed to :			
Owners of the Company	(9)	85	-111%
Non-controlling Interests	-	-	-
Basic EPS	(0.13)	1.23	-111%

FIT

Balance Sheet

(K'USD)	As of 30 June 2023	As of 30 June 2022	ΥοΥ
Cash and Cash equivalents	1,383,557	853,917	62%
Inventory	792,038	1,123,084	-29%
Receivables	614,803	779,536	-21%
Other current assets	135,061	204,583	-34%
Non-current assets	1,694,246	1,872,018	-9%
Total Assets	4,619,705	4,833,138	-4%
Current Liabilities	(2,272,239)	1,796,027	27%
Non-Current Liabilities	(75,263)	662,996	-89%
Total Liabilities	(2,347,502)	2,459,023	-5%
Equity	2,272,203	2,374,115	-4%

Cash Conversion Cycle

Days	1H23	1H22
Average inventory turnover days	105	110
Average trade receivables turnover days	67	79
Average trade payables turnover days	73	78

Terminology

Term	Definition
SiC	Silicon Carbide
48V-DC	48 Voltage DC Power Supply
M-CRPS	Common Redundant Power Supply
DC-HMS	Modular Hardware System
PCle	Peripheral Component Interconnect Express
U.2	Extension of the SATA and SAS storage interfaces
M-XIO	Extensible IO (near side "IO")
EDSFF	Enterprise & Data Centre SSD Form Factor